

Serial No.:

09/467,253

Unit: 2815

Filed:

December 20, 1999

Examiner: C. Chu

For:

WIRE BONDING METHOD FOR COPPER INTERCONNECTS IN

SEMICONDUCTOR DEVICES

RESPONSE TO RESTRICTION REQUIREMENT

Hon. Commissioner of Patents and Trademarks Washington, DC 20231

I hereby certify that, on the date indicated above, this paper or fee was deposited with the U.S. Postal Service & that it was addressed for delivery to the Assistant Commissioner for Patents, Washington, DC 20231 by "Express Mail Post Office to Add/essee service.

Sir:

In response to the Office Action mailed July 10, 2001, kindly consider the following remarks.

It is believed that an extension of time fee is not required with this response. However, the Commissioner is authorized to charge any deficiency in fee, if needed, to deposit Account No. 04-0100.

REMARKS

Reconsideration of this application is respectfully requested. Claims 1-20 are pending and are at issue.

File 3158/0I180US0

RESTRICTION REQUIREMENT

The Examiner has required restriction among the claims of:

Group I (claims 1-15) drawn to a wire bonding method, classified in class 438,

subclass 1+.

Group II (claims 16-20) drawn to a semiconductor device, classified in class 257,

subclass 734.

In response, solely to be responsive to the requirement for restriction, Applicants

provisionally elect with traverse to prosecute the invention of Group I, claim 1-15, drawn to

piezoelectric ceramic resonator.

CONCLUSION

In view of the above remarks, withdrawal of the restriction requirement is respectfully

requested.

Dated: August 6, 2001

Respectfully submitted,

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